

## 256K SPI Bus Serial EEPROM Extended (-55°C to +125°C) Operating Temperatures

### Device Selection Table

Part Number	Vcc Range	Page Size	Temp. Ranges	Packages
25LC256	2.5V-5.5V	64 Byte	M	MF

### Features

- **Maximum Clock 10 MHz**
- Low-Power CMOS Technology:
  - Maximum Write current: 5 mA at 5.5V, 10 MHz
  - Read current: 6 mA at 5.5V, 10 MHz
  - Standby current: 1  $\mu$ A at 5.5V, 85°C
- 32,768 x 8-bit Organization
- 64-Byte Page
- Self-Timed Erase and Write Cycles (5 ms maximum)
- Block Write Protection:
  - Protect none, 1/4, 1/2 or all of array
- Built-In Write Protection:
  - Power-on/off data protection circuitry
  - Write enable latch
  - Write-protect pin
- Sequential Read
- High Reliability:
  - Endurance: 1,000,000 erase/write cycles
  - Data retention: >200 years
  - ESD protection: >4000V
- Temperature Ranges Supported:
  - Extended (M): -55°C to +125°C
- RoHS Compliant

### Pin Function Table

Name	Function
$\overline{\text{CS}}$	Chip Select Input
SO	Serial Data Output
$\overline{\text{WP}}$	Write-Protect
Vss	Ground
SI	Serial Data Input
SCK	Serial Clock Input
$\overline{\text{HOLD}}$	Hold Input
Vcc	Supply Voltage

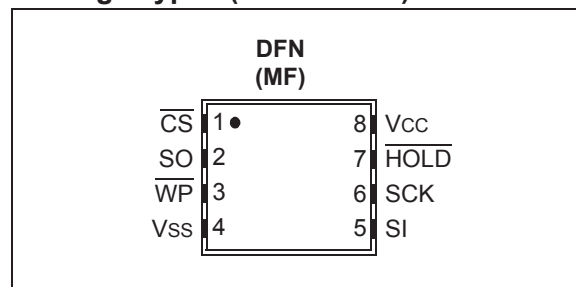
### Description

The Microchip Technology Inc. 25LC256 is a 256 Kbit Serial Electrically Erasable PROM. The memory is accessed via a simple Serial Peripheral Interface (SPI) compatible serial bus. The bus signals required are a clock input (SCK) plus separate data in (SI) and data out (SO) lines. Access to the device is controlled through a Chip Select ( $\overline{\text{CS}}$ ) input.

Communication to the device can be paused via the hold pin (HOLD). While the device is paused, transitions on its inputs will be ignored, with the exception of Chip Select, allowing the host to service higher priority interrupts.

The 25LC256 is available in the 8-lead DFN package.

### Package Types (not to scale)



# 25LC256

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings <sup>(†)</sup>

V <sub>CC</sub> .....	6.5V
All inputs and outputs w.r.t. V <sub>SS</sub> .....	-0.6V to V <sub>CC</sub> +1.0V
Storage temperature .....	-65°C to 150°C
Ambient temperature under bias .....	-55°C to 125°C
ESD protection on all pins .....	4 kV

† **NOTICE:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for an extended period of time may affect device reliability.

**TABLE 1-1: DC CHARACTERISTICS**

DC CHARACTERISTICS			Extended (M):    TA = -55°C to +125°C    VCC = 2.5V to 5.5V			
Param. No.	Symbol	Characteristic	Min.	Max.	Units	Test Conditions
D1	VIH	High-Level Input Voltage	0.7 VCC	VCC + 1	V	
D2	VIL	Low-Level Input Voltage	-0.3	0.3 VCC	V	VCC ≥ 2.5V
D3	VIL		-0.3	0.2 VCC	V	VCC < 2.5V
D4	VOL	Low-Level Output Voltage	—	0.4	V	IoL = 2.1 mA, VCC = 4.5V
D5	VOL		—	0.2	V	IoL = 1.0 mA, VCC = 2.5V
D6	VOH	High-Level Output Voltage	VCC – 0.5	—	V	IoH = -400 µA
D7	ILI	Input Leakage Current	—	±1	µA	$\overline{\text{CS}}$ = VCC, VIN = VSS or VCC
D8	ILO	Output Leakage Current	—	±1	µA	$\overline{\text{CS}}$ = VCC, VOUT = VSS or VCC
D9	CINT	Internal Capacitance (all inputs and outputs)	—	7	pF	TA = 25°C, FCLK = 1.0 MHz, VCC = 5.0V ( <b>Note 1</b> )
D10	ICCREAD	Operating Current	—	6	mA	VCC = 5.5V; FCLK = 10.0 MHz; SO = Open
			—	2.5	mA	VCC = 2.5V; FCLK = 5.0 MHz; SO = Open
D11	ICCWRITE		—	5	mA	VCC = 5.5V
			—	3	mA	VCC = 2.5V
D12	ICCS	Standby Current	—	5	µA	$\overline{\text{CS}}$ = VCC = 5.5V, Inputs tied to VCC or VSS, 125°C
			—	1	µA	$\overline{\text{CS}}$ = VCC = 5.5V, Inputs tied to VCC or VSS, 85°C

**Note 1:** This parameter is periodically sampled and not 100% tested.

TABLE 1-2: AC CHARACTERISTICS

AC CHARACTERISTICS			Extended (M): TA = -55°C to +125°C VCC = 2.5V to 5.5V			
Param. No.	Symbol	Characteristic	Min.	Max.	Units	Test Conditions
1	FCLK	Clock Frequency	—	10	MHz	4.5V ≤ VCC ≤ 5.5V
			—	5	MHz	2.5V ≤ VCC < 4.5V
2	TCSS	CS Setup Time	50	—	ns	4.5V ≤ VCC ≤ 5.5V
			100	—	ns	2.5V ≤ VCC < 4.5V
3	TCSH	CS Hold Time	100	—	ns	4.5V ≤ VCC ≤ 5.5V
			200	—	ns	2.5V ≤ VCC < 4.5V
4	TCSD	CS Disable Time	50	—	ns	
5	TSU	Data Setup Time	10	—	ns	4.5V ≤ VCC ≤ 5.5V
			20	—	ns	2.5V ≤ VCC < 4.5V
6	THD	Data Hold Time	20	—	ns	4.5V ≤ VCC ≤ 5.5V
			40	—	ns	2.5V ≤ VCC < 4.5V
7	TR	CLK Rise Time	—	100	ns	Note 1
8	TF	CLK Fall Time	—	100	ns	Note 1
9	THI	Clock High Time	50	—	ns	4.5V ≤ VCC ≤ 5.5V
			100	—	ns	2.5V ≤ VCC < 4.5V
10	TLO	Clock Low Time	50	—	ns	4.5V ≤ VCC ≤ 5.5V
			100	—	ns	2.5V ≤ VCC < 4.5V
11	TCLD	Clock Delay Time	50	—	ns	
12	TCLE	Clock Enable Time	50	—	ns	
13	TV	Output Valid from Clock Low	—	50	ns	4.5V ≤ VCC ≤ 5.5V
			—	100	ns	2.5V ≤ VCC < 4.5V
14	THO	Output Hold Time	0	—	ns	Note 1
15	TDIS	Output Disable Time	—	40	ns	4.5V ≤ VCC ≤ 5.5V (Note 1)
			—	80	ns	2.5V ≤ VCC < 4.5V (Note 1)
16	THS	HOLD Setup Time	20	—	ns	4.5V ≤ VCC ≤ 5.5V
			40	—	ns	2.5V ≤ VCC < 4.5V
17	THH	HOLD Hold Time	20	—	ns	4.5V ≤ VCC ≤ 5.5V
			40	—	ns	2.5V ≤ VCC < 4.5V
18	THZ	HOLD Low to Output High Z	30	—	ns	4.5V ≤ VCC ≤ 5.5V (Note 1)
			60	—	ns	2.5V ≤ VCC < 4.5V (Note 1)
19	THV	HOLD High to Output Valid	30	—	ns	4.5V ≤ VCC ≤ 5.5V
			60	—	ns	2.5V ≤ VCC < 4.5V
20	TWC	Internal Write Cycle Time	—	5	ms	Note 2
21		Endurance	1M	—	E/W Cycles	25°C, VCC = 5.5V (Note 3)

**Note 1:** This parameter is periodically sampled and not 100% tested.

**2:** Twc begins on the rising edge of  $\overline{\text{CS}}$  after a valid write sequence and ends when the internal write cycle is complete.

**3:** This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained from Microchip's website at [www.microchip.com](http://www.microchip.com).

TABLE 1-3: AC TEST CONDITIONS

AC Waveform:	
$V_{LO} = 0.2V$	—
$V_{HI} = V_{CC} - 0.2V$	Note 1
$V_{HI} = 4.0V$	Note 2
$C_L = 50\text{ pF}$	—
Timing Measurement Reference Level	
Input	$0.5 V_{CC}$
Output	$0.5 V_{CC}$

Note 1: For  $V_{CC} \leq 4.0V$   
2: For  $V_{CC} > 4.0V$

FIGURE 1-1: HOLD TIMING

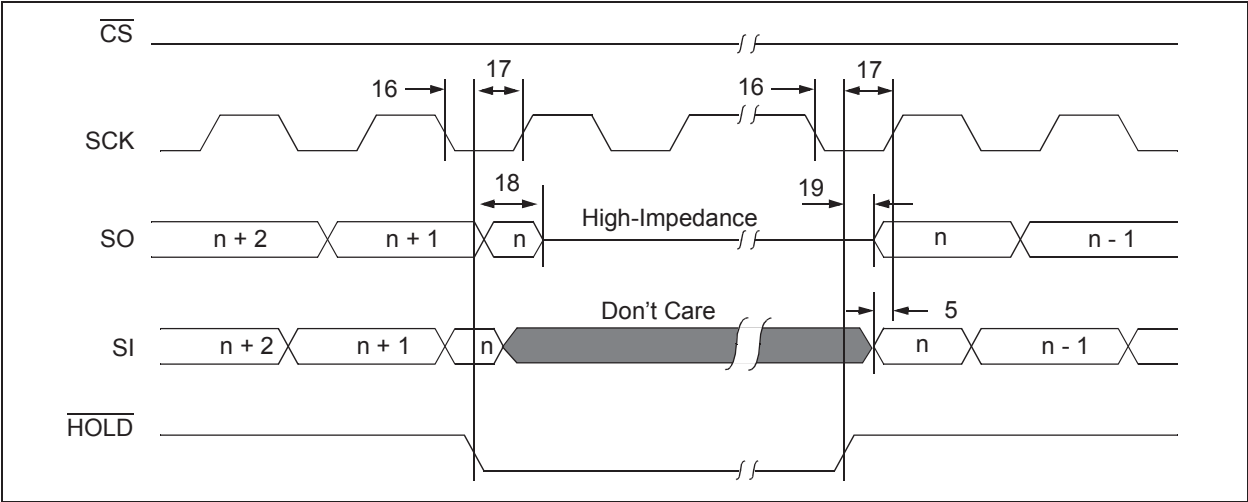
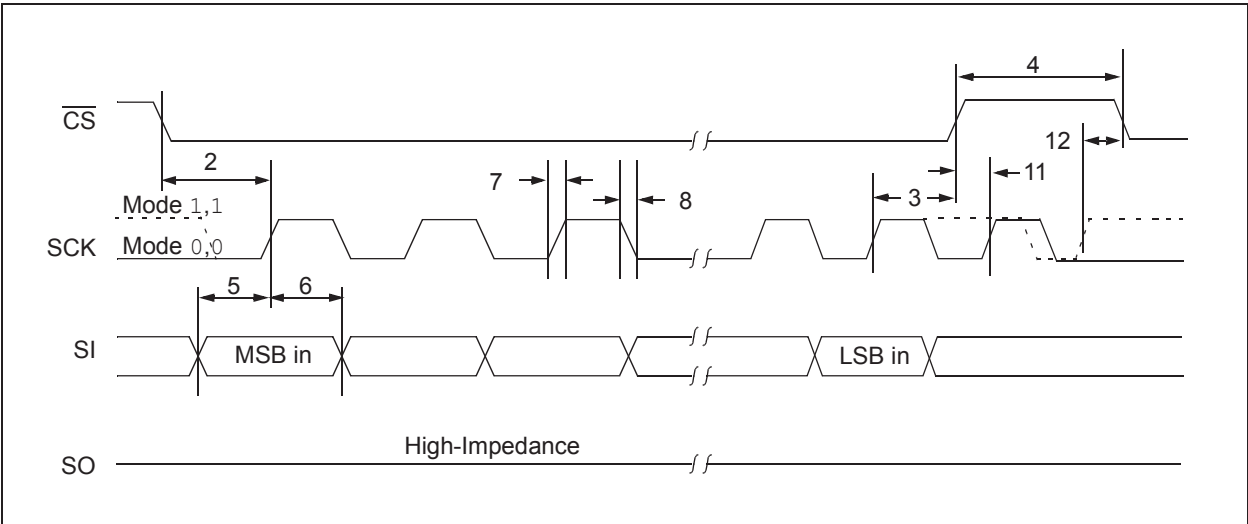
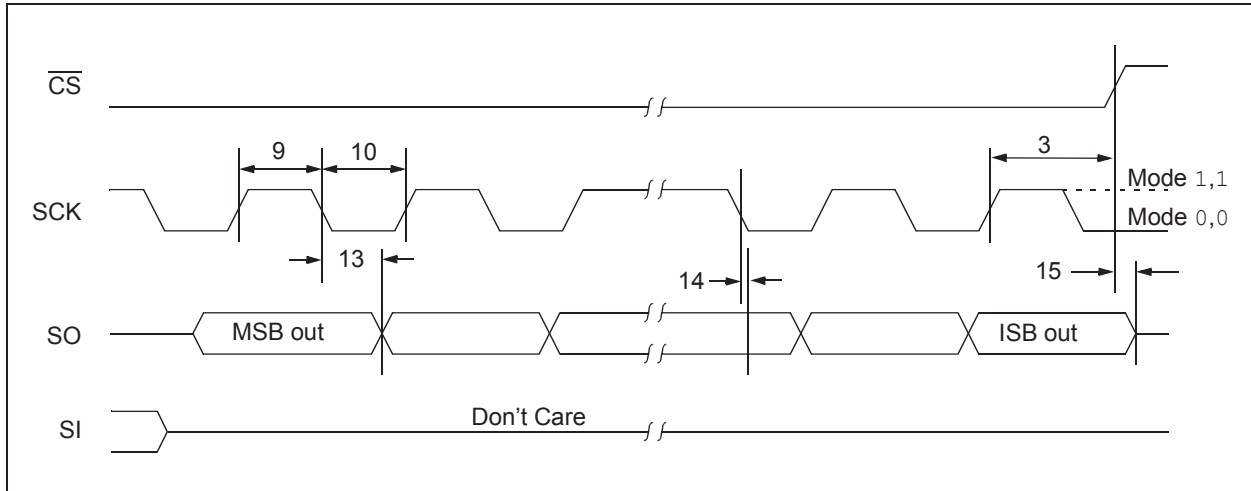


FIGURE 1-2: SERIAL INPUT TIMING



**FIGURE 1-3: SERIAL OUTPUT TIMING**



## 2.0 FUNCTIONAL DESCRIPTION

### 2.1 Principles of Operation

The 25LC256 is a 32,768-byte Serial EEPROM designed to interface directly with the Serial Peripheral Interface (SPI) port of many of today's popular microcontroller families, including Microchip's PIC® microcontrollers. It may also interface with microcontrollers that do not have a built-in SPI port by using discrete I/O lines programmed properly in firmware to match the SPI protocol.

The 25LC256 contains an 8-bit instruction register. The device is accessed via the SI pin, with data being clocked in on the rising edge of SCK. The  $\overline{\text{CS}}$  pin must be low and the HOLD pin must be high for the entire operation.

Table 2-1 contains a list of the possible instruction bytes and format for device operation. All instructions, addresses, and data are transferred MSB first, LSB last.

Data (SI) is sampled on the first rising edge of SCK after  $\overline{\text{CS}}$  goes low. If the clock line is shared with other peripheral devices on the SPI bus, the user can assert the HOLD input and place the 25LC256 in 'HOLD' mode. After releasing the  $\overline{\text{HOLD}}$  pin, operation will resume from the point when the  $\overline{\text{HOLD}}$  was asserted.

### 2.2 Read Sequence

The device is selected by pulling  $\overline{\text{CS}}$  low. The 8-bit READ instruction is transmitted to the 25LC256 followed by the 16-bit address, with the first MSB of the address being a "don't care" bit. After the correct READ instruction and address are sent, the data stored in the memory at the selected address is shifted out on the SO pin. The data stored in the memory at the next address can be read sequentially by continuing to provide clock pulses. The internal Address Pointer is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached (7FFFh), the address counter rolls over to address 0000h allowing the read cycle to be continued indefinitely. The read operation is terminated by raising the  $\overline{\text{CS}}$  pin (Figure 2-1).

### 2.3 Write Sequence

Prior to any attempt to write data to the 25LC256, the write enable latch must be set by issuing the  $\overline{\text{WREN}}$  instruction (Figure 2-4). This is done by setting  $\overline{\text{CS}}$  low and then clocking out the proper instruction into the 25LC256. After all eight bits of the instruction are transmitted, the  $\overline{\text{CS}}$  must be brought high to set the write enable latch. If the write operation is initiated immediately after the  $\overline{\text{WREN}}$  instruction without  $\overline{\text{CS}}$  being brought high, the data will not be written to the array because the write enable latch will not have been properly set.

Once the write enable latch is set, the user may proceed by setting the  $\overline{\text{CS}}$  low, issuing a  $\overline{\text{WRITE}}$  instruction, followed by the 16-bit address, with the first MSB of the address being a "don't care" bit, and then the data to be written. Up to 64 bytes of data can be sent to the device before a write cycle is necessary. The only restriction is that all of the bytes must reside in the same page.

**Note:** Page write operations are limited to writing bytes within a single physical page, **regardless** of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page size') and, end at addresses that are integer multiples of page size – 1. If a Page Write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

For the data to be actually written to the array, the  $\overline{\text{CS}}$  must be brought high after the Least Significant bit (D0) of the  $n^{\text{th}}$  data byte has been clocked in. If  $\overline{\text{CS}}$  is brought high at any other time, the write operation will not be completed. Refer to Figure 2-2 and Figure 2-3 for more detailed illustrations on the byte write sequence and the page write sequence, respectively. While the write is in progress, the STATUS register may be read to check the status of the WPEN, WIP, WEL, BP1 and BP0 bits (Figure 2-6). A read attempt of a memory array location will not be possible during a write cycle. When the write cycle is completed, the write enable latch is reset.

BLOCK DIAGRAM

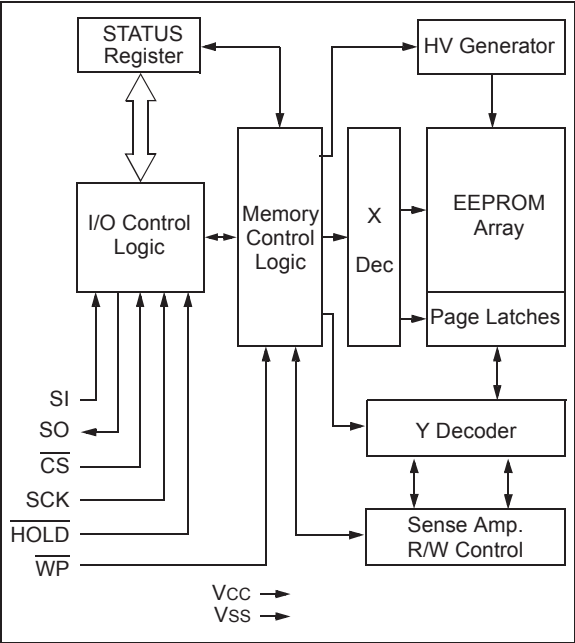


TABLE 2-1: INSTRUCTION SET

Instruction Name	Instruction Format	Description
READ	0000 0011	Read data from memory array beginning at selected address
WRITE	0000 0010	Write data to memory array beginning at selected address
WRDI	0000 0100	Reset the write enable latch (disable write operations)
WREN	0000 0110	Set the write enable latch (enable write operations)
RDSR	0000 0101	Read STATUS register
WRSR	0000 0001	Write STATUS register

FIGURE 2-1: READ SEQUENCE

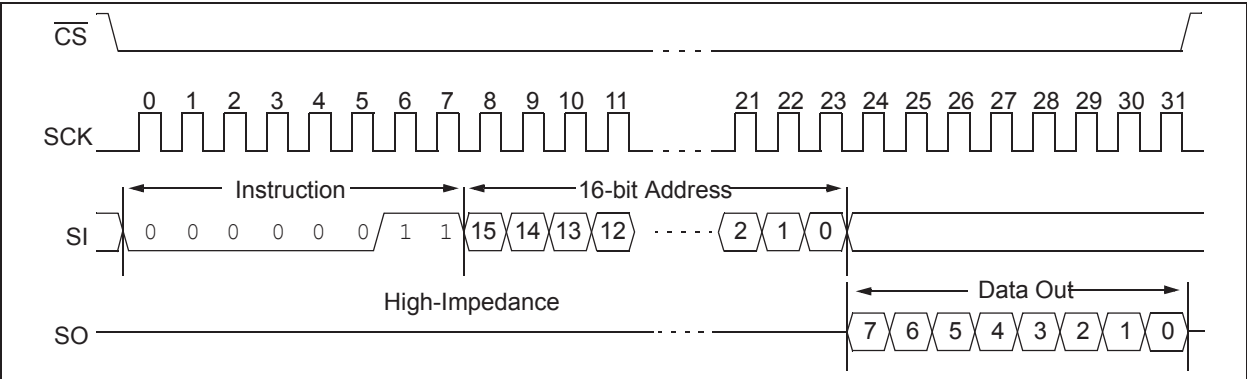


FIGURE 2-2: BYTE WRITE SEQUENCE

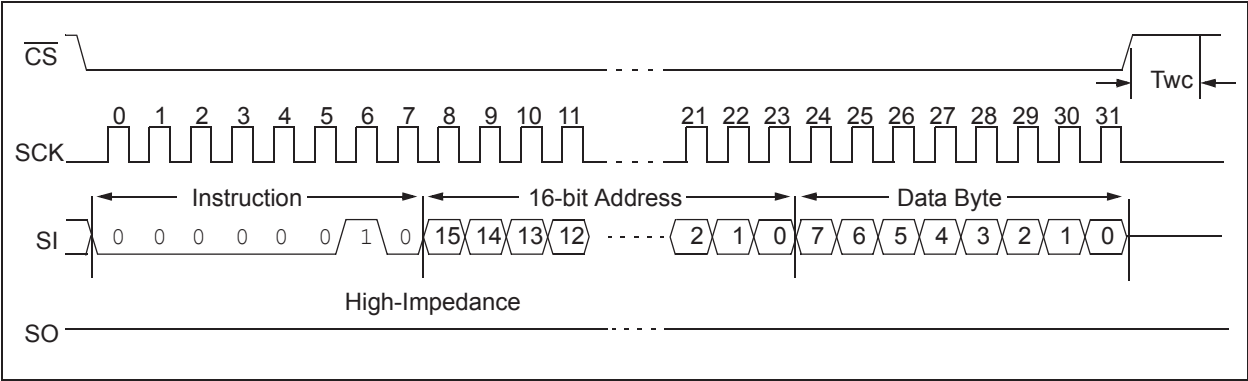
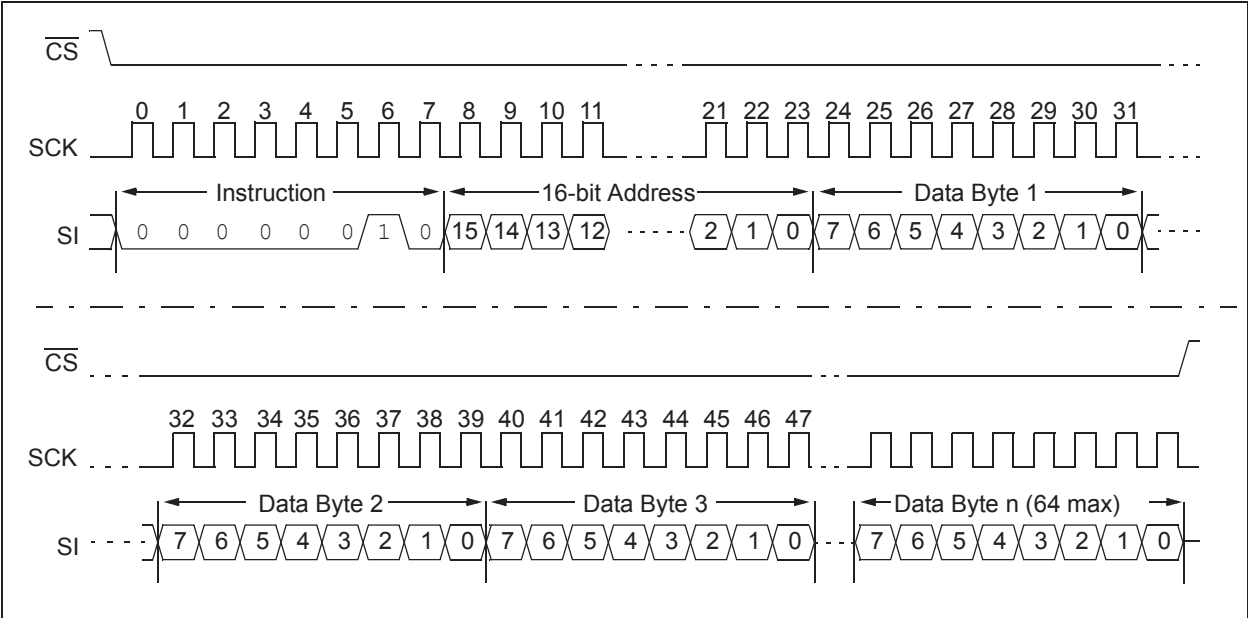


FIGURE 2-3: PAGE WRITE SEQUENCE





2.4 Write Enable (WREN) and Write Disable (WRDI)

The 25LC256 contains a write enable latch. See [Table 2-1](#) for the Write-Protect Functionality Matrix. This latch must be set before any write operation will be completed internally. The WREN instruction will set the latch, and the WRDI will reset the latch.

The following is a list of conditions under which the write enable latch will be reset:

- Power-up
- WRDI instruction successfully executed
- WRSR instruction successfully executed
- WRITE instruction successfully executed

FIGURE 2-4: WRITE ENABLE SEQUENCE (WREN)

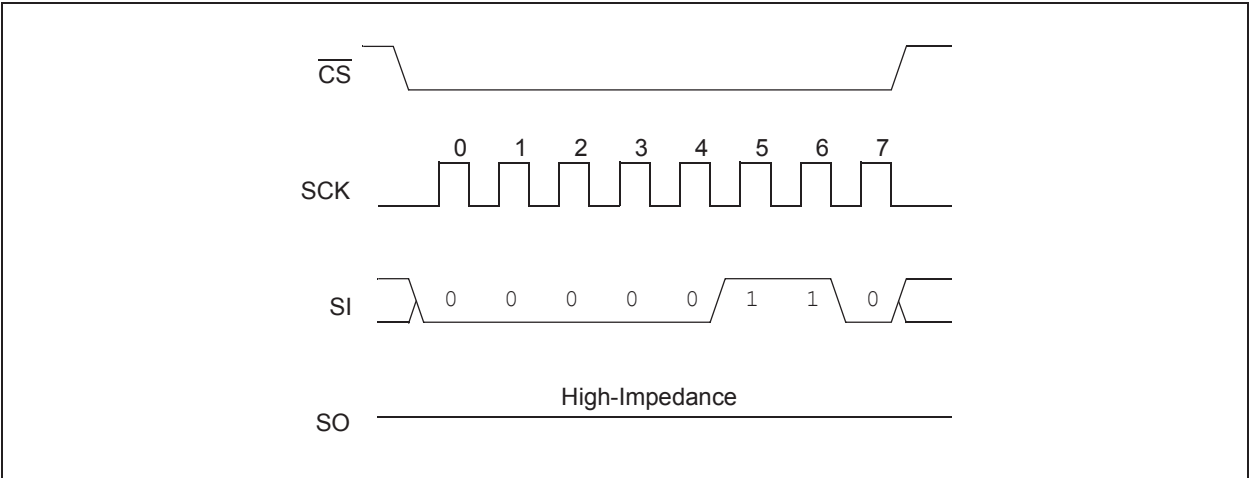
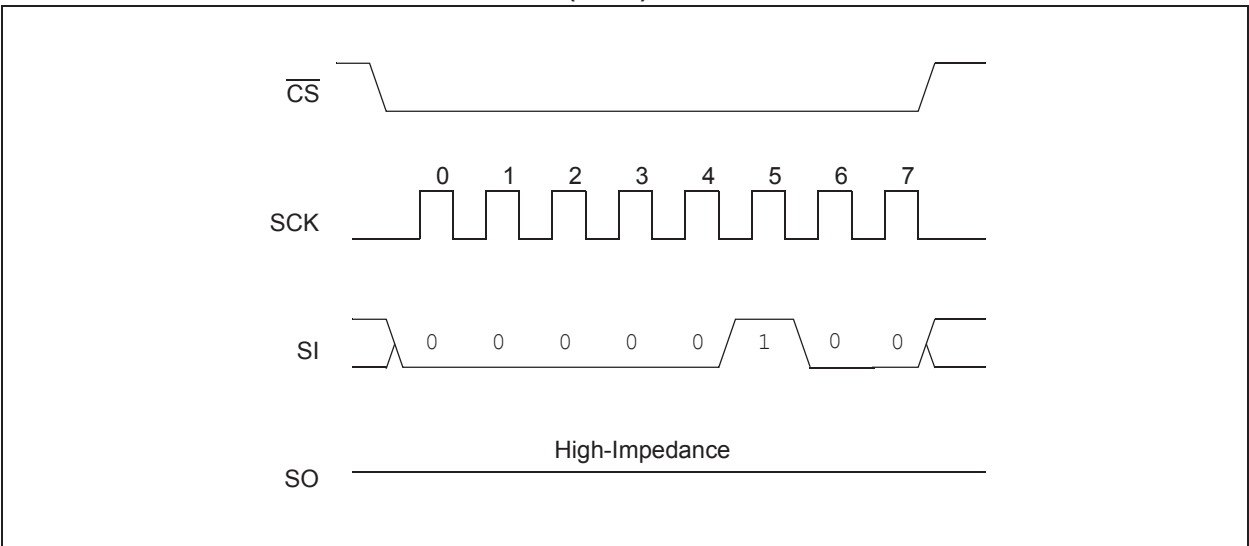


FIGURE 2-5: WRITE DISABLE SEQUENCE (WRDI)



2.5 Read Status Register Instruction (RDSR)

The Read Status Register instruction (RDSR) provides access to the STATUS register. The STATUS register may be read at any time, even during a write cycle. The STATUS register is formatted as follows:

TABLE 2-2: STATUS REGISTER

7	6	5	4	3	2	1	0
W/R	-	-	-	W/R	W/R	R	R
WPEN	x	x	x	BP1	BP0	WEL	WIP

W/R = writable/readable. R = read-only.

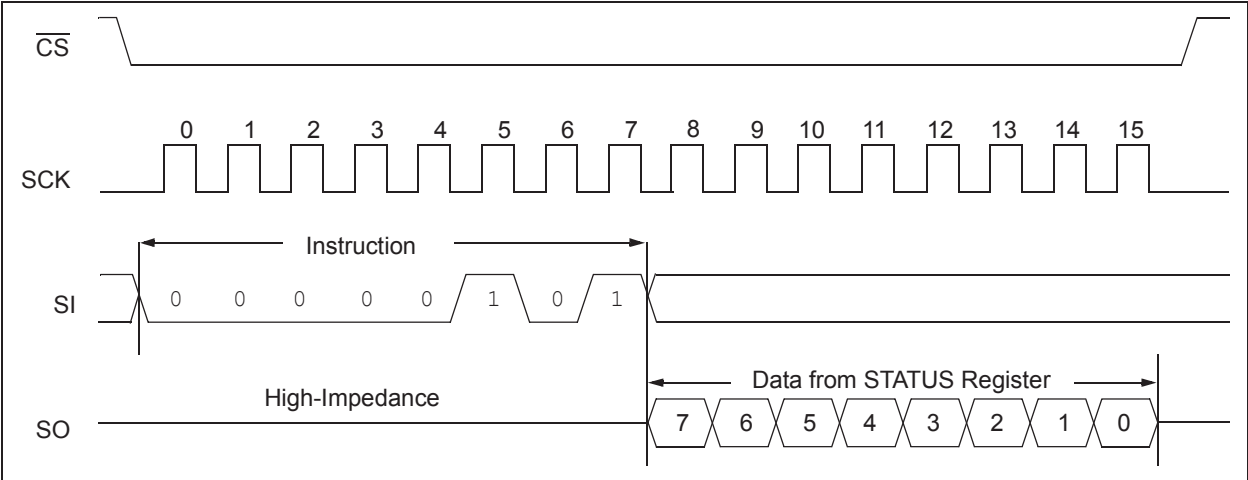
The **Write-In-Process (WIP)** bit indicates whether the 25LC256 is busy with a write operation. When set to a '1', a write is in progress, when set to a '0', no write is in progress. This bit is read-only.

The **Write Enable Latch (WEL)** bit indicates the status of the write enable latch and is read-only. When set to a '1', the latch allows writes to the array, when set to a '0', the latch prohibits writes to the array. The state of this bit can always be updated via the `WREN` or `WRDI` commands, regardless of the state of write protection on the STATUS register. These commands are shown in [Figure 2-4](#) and [Figure 2-5](#).

The **Block Protection (BP0 and BP1)** bits indicate which blocks are currently write-protected. These bits are set by the user issuing the `WRSR` instruction. These bits are nonvolatile, and are shown in [Table 2-3](#).

See [Figure 2-6](#) for the RDSR timing sequence.

FIGURE 2-6: READ STATUS REGISTER TIMING SEQUENCE (RDSR)



## 2.6 Write Status Register Instruction (WRSR)

The Write Status Register instruction (WRSR) allows the user to write to the nonvolatile bits in the STATUS register as shown in Table 2-2. The user is able to select one of four levels of protection for the array by writing to the appropriate bits in the STATUS register. The array is divided up into four segments. The user has the ability to write-protect none, one, two, or all four of the segments of the array. The partitioning is controlled as shown in Table 2-3.

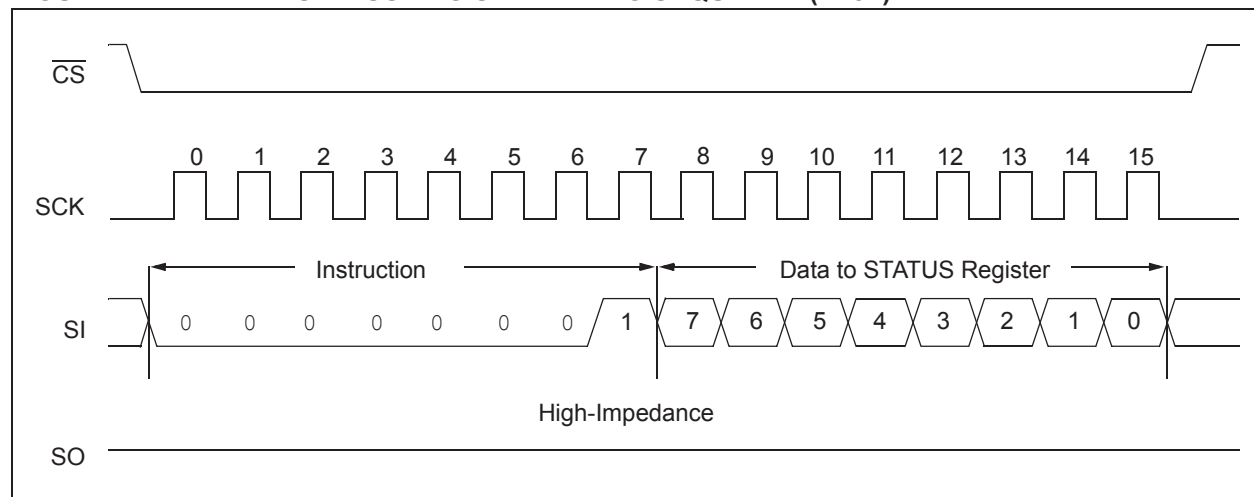
The Write-Protect Enable (WPEN) bit is a nonvolatile bit that is available as an enable bit for the  $\overline{\text{WP}}$  pin. The Write-Protect ( $\overline{\text{WP}}$ ) pin and the Write-Protect Enable (WPEN) bit in the STATUS register control the programmable hardware write-protect feature. Hardware write protection is enabled when  $\overline{\text{WP}}$  pin is low and the WPEN bit is high. Hardware write protection is disabled when either the  $\overline{\text{WP}}$  pin is high or the WPEN bit is low. When the chip is hardware write-protected, only writes to nonvolatile bits in the STATUS register are disabled. See Table 2-1 for a matrix of functionality on the WPEN bit.

See Figure 2-7 for the WRSR timing sequence.

**TABLE 2-3: ARRAY PROTECTION**

BP1	BP0	Array Addresses Write-Protected
0	0	none
0	1	upper 1/4 (6000h-7FFFh)
1	0	upper 1/2 (4000h-7FFFh)
1	1	all (0000h-7FFFh)

**FIGURE 2-7: WRITE STATUS REGISTER TIMING SEQUENCE (WRSR)**



**Note:** An internal write cycle (T<sub>wc</sub>) is initiated on the rising edge of  $\overline{\text{CS}}$  after a valid write STATUS register sequence.

## 2.7 Data Protection

The following protection has been implemented to prevent inadvertent writes to the array:

- The write enable latch is reset on power-up
- A write enable instruction must be issued to set the write enable latch
- After a byte write, page write or STATUS register write, the write enable latch is reset
- $\overline{CS}$  must be set high after the proper number of clock cycles to start an internal write cycle
- Access to the array during an internal write cycle is ignored and programming is continued

## 2.8 Power-On State

The 25LC256 powers on in the following state:

- The device is in low-power Standby mode ( $\overline{CS} = 1$ )
- The write enable latch is reset
- SO is in high-impedance state
- A high-to-low-level transition on  $\overline{CS}$  is required to enter active state

**TABLE 2-1: WRITE-PROTECT FUNCTIONALITY MATRIX**

WEL (SR bit 1)	WPEN (SR bit 7)	$\overline{WP}$ pin	Protected Blocks	Unprotected Blocks	STATUS Register
0	x	x	Protected	Protected	Protected
1	0	x	Protected	Writable	Writable
1	1	0 (low)	Protected	Writable	Protected
1	1	1 (high)	Protected	Writable	Writable

x = don't care

### 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 3-1](#).

**TABLE 3-1: PIN FUNCTION TABLE**

Name	DFN	Function
$\overline{\text{CS}}$	1	Chip Select Input
SO	2	Serial Data Output
$\overline{\text{WP}}$	3	Write-Protect Pin
Vss	4	Ground
SI	5	Serial Data Input
SCK	6	Serial Clock Input
$\overline{\text{HOLD}}$	7	Hold Input
Vcc	8	Supply Voltage

#### 3.1 Chip Select ( $\overline{\text{CS}}$ )

A low level on this pin selects the device. A high level deselects the device and forces it into Standby mode. However, a programming cycle which is already initiated or in progress will be completed, regardless of the  $\overline{\text{CS}}$  input signal. If  $\overline{\text{CS}}$  is brought high during a program cycle, the device will go into Standby mode as soon as the programming cycle is complete. When the device is deselected, SO goes to the high-impedance state, allowing multiple parts to share the same SPI bus. A low-to-high transition on  $\overline{\text{CS}}$  after a valid write sequence initiates an internal write cycle. After power-up, a low level on  $\overline{\text{CS}}$  is required prior to any sequence being initiated.

#### 3.2 Serial Output (SO)

The SO pin is used to transfer data out of the 25LC256. During a read cycle, data is shifted out on this pin after the falling edge of the serial clock.

#### 3.3 Write-Protect ( $\overline{\text{WP}}$ )

This pin is used in conjunction with the WPEN bit in the STATUS register to prohibit writes to the nonvolatile bits in the STATUS register. When  $\overline{\text{WP}}$  is low and WPEN is high, writing to the nonvolatile bits in the STATUS register is disabled. All other operations function normally. When  $\overline{\text{WP}}$  is high, all functions, including writes to the nonvolatile bits in the STATUS register, operate normally. If the WPEN bit is set,  $\overline{\text{WP}}$  low during a STATUS register write sequence will disable writing to the STATUS register. If an internal write cycle has already begun,  $\overline{\text{WP}}$  going low will have no effect on the write.

The  $\overline{\text{WP}}$  pin function is blocked when the WPEN bit in the STATUS register is low. This allows the user to install the 25LC256 in a system with  $\overline{\text{WP}}$  pin grounded and still be able to write to the STATUS register. The WP pin functions will be enabled when the WPEN bit is set high.

#### 3.4 Serial Input (SI)

The SI pin is used to transfer data into the device. It receives instructions, addresses and data. Data is latched on the rising edge of the serial clock.

#### 3.5 Serial Clock (SCK)

The SCK is used to synchronize the communication between a master and the 25LC256. Instructions, addresses or data present on the SI pin are latched on the rising edge of the clock input, while data on the SO pin is updated after the falling edge of the clock input.

#### 3.6 Hold ( $\overline{\text{HOLD}}$ )

The  $\overline{\text{HOLD}}$  pin is used to suspend transmission to the 25LC256 while in the middle of a serial sequence without having to retransmit the entire sequence again. It must be held high any time this function is not being used. Once the device is selected and a serial sequence is underway, the  $\overline{\text{HOLD}}$  pin may be pulled low to pause further serial communication without resetting the serial sequence. The HOLD pin must be brought low while SCK is low, otherwise the HOLD function will not be invoked until the next SCK high-to-low transition. The 25LC256 must remain selected during this sequence. The SI, SCK and SO pins are in a high-impedance state during the time the device is paused and transitions on these pins will be ignored. To resume serial communication, HOLD must be brought high while the SCK pin is low, otherwise serial communication will not resume. Lowering the HOLD line at any time will tri-state the SO line.

# 25LC256

## 4.0 PACKAGING INFORMATION

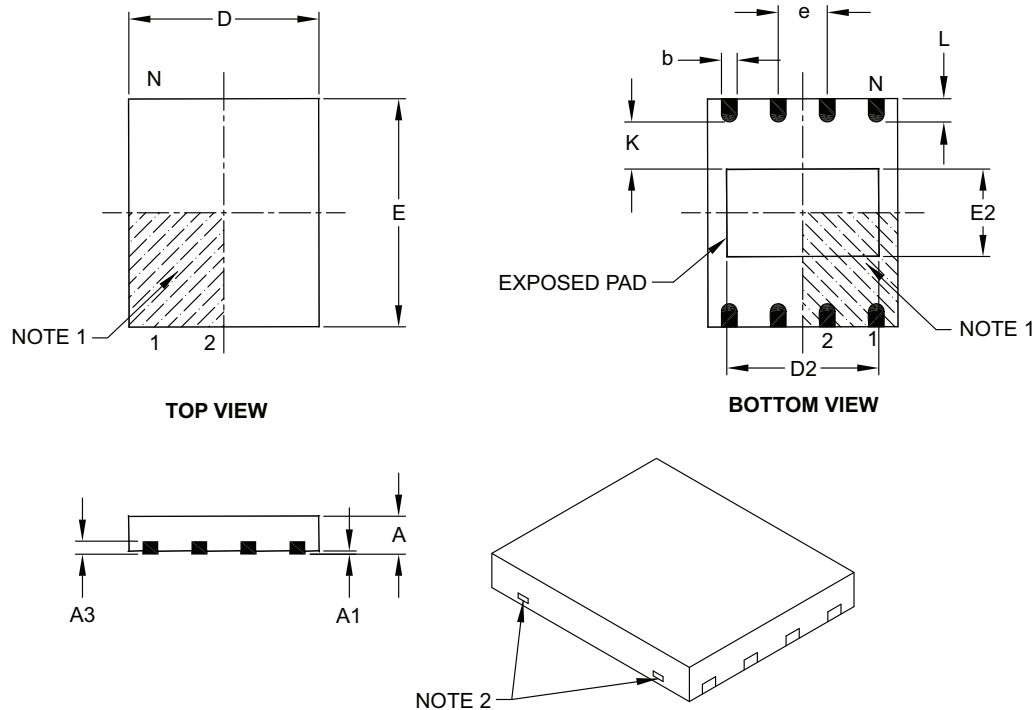
### 4.1 Package Marking Information



<b>Legend:</b>	XX...X	Part number or part number code
	T	Temperature (M)
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code (2 characters for small packages)
	<sup>(e3)</sup>	JEDEC <sup>®</sup> designator for Matte Tin (Sn)
<b>Note:</b>	For very small packages with no room for the JEDEC <sup>®</sup> designator <sup>(e3)</sup> , the marking will only appear on the outer carton or reel label.	
<b>Note:</b>	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.	

## 8-Lead Plastic Dual Flat, No Lead Package (MF) – 6x5 mm Body [DFN-S]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	0.80	0.85	1.00
Standoff	A1	0.00	0.01	0.05
Contact Thickness	A3	0.20 REF		
Overall Length	D	5.00 BSC		
Overall Width	E	6.00 BSC		
Exposed Pad Length	D2	3.90	4.00	4.10
Exposed Pad Width	E2	2.20	2.30	2.40
Contact Width	b	0.35	0.40	0.48
Contact Length	L	0.50	0.60	0.75
Contact-to-Exposed Pad	K	0.20	–	–

### Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package may have one or more exposed tie bars at ends.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

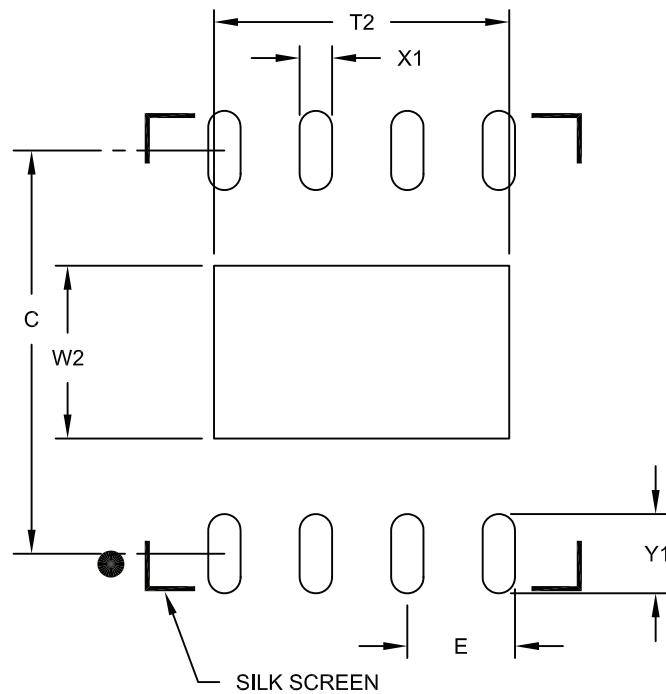
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-122B

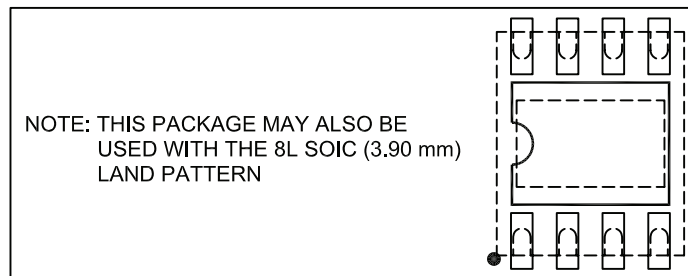
# 25LC256

## 8-Lead Plastic Dual Flat, No Lead Package (MF) - 6x5 mm Body [DFN-S]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Optional Center Pad Width	W2			2.40
Optional Center Pad Length	T2			4.10
Contact Pad Spacing	C		5.60	
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.10

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2122A



## APPENDIX A: REVISION HISTORY

### Revision A (02/2017)

Initial release of this document.

# 25LC256

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NOTES:

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# 25LC256

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NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>/X/</u> <sup>(1)</sup>	<u>X</u>	<u>/XX</u>
Device	Tape and Reel Option	Temperature Range	Package
<b>Device:</b>	25LC256	256 Kbit, 2.5V, 64-Byte Page, SPI Serial EEPROM	
<b>Tape &amp; Reel:</b>	Blank = Standard packaging (tube) T = Tape & Reel <sup>(1)</sup>		
<b>Temperature Range:</b>	M = -55°C to +125°C		
<b>Package:</b>	MF = Micro Lead Frame (6 x 5 mm body), 8-lead		

**Examples:**

a) 25LC256-M/MF = 256 Kbit, 2.5V Serial EEPROM, Extended temp., DFN package.

b) 25LC256T-M/MF = 256 Kbit, 2.5V Serial EEPROM, Tape & Reel, Extended temp., DFN package.

**Note 1:** Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

# 25LC256

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NOTES:

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**Note the following details of the code protection feature on Microchip devices:**

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- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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- Microchip is willing to work with the customer who is concerned about the integrity of their code.
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